

Hole-plugging service at I.T.C. Intercircuit Production GmbH

I.T.C. Intercircuit Production GmbH offers the „Via Hole Plugging“ service since 2003. The air-bubble-free hole filling according to IPC 6012 is done under vacuum with our patented filling-head-system and offers following advantages:

- Filling of Through and Blind holes in one step
- Selective plugging is possible (masking tape required)
- Reference holes are taped of and will not be filled with paste
- Plugging of multilayer panels and inner layers
- Perfect planarity on the panel surface due to a special grinding method
- Aspect Ratio up to 40:1
- Minimum hole diameter: 0,1 mm (after plating)
- Maximum hole diameter: AR 1:1, up to 2 mm
- Panel thickness: 0,3 mm - 10 mm
- Panel dimensions: min: 200 mm x 200 mm, max: 610 mm x 1016 mm



All hole-filling-systems were developed by I.T.C. Intercircuit and are patented. Prior the hole-plugging-process the panels are pre-baked to remove any remaining moisture. We offer as a standard to fill with Taiyo THP-100 DX1 VF HV and HTG paste (other pastes on request).



Hole filling machine THP 35-01 + THP 35



Hole filling machine CF 200

After final cure the panels are grinded on the "Wise" fully automated grinding system or on our I.T.C. wet grinding machine PD 50. If requested we will issue a copper measurement protocol for your quality control.

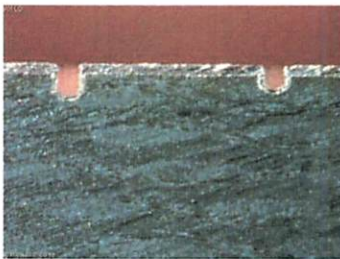


Wise grinding system Cleverstar

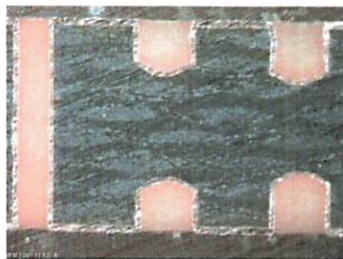


Wet grinding machine PD 50

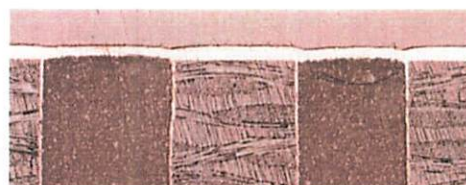
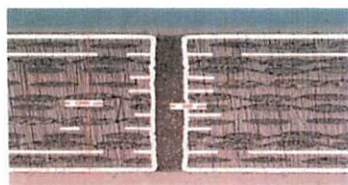
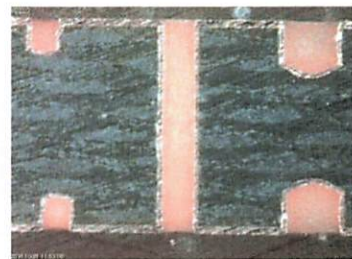
Results for Through and Blind holes filled on a THP 35



plugged and grinded, hole 0,2 mm



plugged and plated



We offer a free of charge test of up to 5 panels to show our capabilities.
Please contact us:

I.T.C. Intercircuit Production GmbH

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